

## **International Electronics Week in Central and South-Eastern Europe – Second Edition**

During the 25<sup>th</sup> – 30<sup>th</sup> of October 2021, a unique "International Electronics Week in Central and South-Eastern Europe" will be organized for the second time as an online event. This live scientific event coalesces three main events held traditionally in Romania: TIE, TIEPlus ([www.tie.ro](http://www.tie.ro)), and SIITME ([www.siitme.ro](http://www.siitme.ro)).

The 6<sup>th</sup> edition of the TIEPlus contest, on Monday the 25<sup>th</sup> of October, is the final stage in the industrial certification of the students' knowledge in signal and power integrity and virtual prototyping. The event is followed by a scientific workshop debating various topics, such as electrical, mechanical, and thermal issues of multi-layer chip capacitors.

Tuesday, the 26<sup>th</sup> of October, is dedicated to the 30<sup>th</sup> edition of the TIE computer-aided design contest. The evaluation teams (composed of academic and industrial members) evaluate the contestants' design results in the afternoon. The list of participants, who have met the conditions of being certified PCB designers, is established during the TIE committees' meeting in the evening.

On Wednesday, the 27<sup>th</sup> of October, several workshops will be held. In the morning, the introduction to the EU Pact for Skills initiative, hosted under the HIR-roof of "Electronic Industry-Academy, Strategic Partnership," will be discussed, followed by a debate on "TIE subject demystification" and the TIE/TIEPlus awarding ceremony. In the afternoon, four sessions of Professional Development Hours will be provided free of charge to all participants, students, researchers, engineers, and academic staff. The day ends with the annual IEEE Hungary & Romania EPS & NTC Joint Chapter Meeting.

On Thursday and Friday, 28<sup>th</sup> and 29<sup>th</sup> of October, the 27<sup>th</sup> International Symposium for Design and Technology in Electronic Packaging (SIITME) conference will deliver its dense program with oral, industrial, and poster sessions. Esteemed distinguished lecturers from both EPS and NTC and other invited speakers will deliver a total of 6 Keynote presentations during the two days. On Friday, late afternoon, an IEEE and IMAPS Student Branch Chapter meeting will also be held.

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